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Packaging Market For Compound Semiconductor By Packaging Platform (Flip Chip, Embedded Die, Fan-In WLP, and Fan-Out WLP), Application (CS Power Electronics, CS RF/Microwave, CS Photonics, CS Sensing, and CS Quantum), and End User (Digital Economy, Industrial and Energy & Power, Defense/Security, Transport, Consumer Electronics, Healthcare, and Space): Global Opportunity Analysis and Industry Forecast, 2020–2027

https://marketpublishers.com/r/P66DD2B62A69EN.html
Date: September 2020
Pages: 205
Price: US$ 6,168.00 (Single User License)
ID: P66DD2B62A69EN

Abstracts

The global packaging market for compound semiconductor size was valued at $11.63 billion in 2019, and is projected to reach $25.61 billion by 2027, growing at a CAGR of 10.4% from 2020 to 2027. Compound semiconductors are produced by laminating the layers composed of two or more elements with a thickness ranging from several nanometers to micrometers and it uses different combinations of elements in each layer.

The wafer process differs according to material properties. Moreover, some CS devices contain fragile air bridges, gold bond pads, topographical cavities & trenches, and have a number of unique bulk material properties which are sensitive to the mechanical and chemical processes associated with standard packaging technique.

Thus, the standard electronics packaging and interconnection technologies have become the limiting factor determining the performance and efficiency of the new semiconductor components. Whereas, the advanced packaging technology provides several advantages such as prevention from physical damage, maximize operational

efficiency, and reduces overall cost.

In addition, in consumer electronics and industrial products advance packaging relies on mechanical engineering principles such as dynamics, stress analysis, heat transfer, and fluid mechanics and protects components from mechanical damage, cooling, RF noise emission, and electrostatic discharge. Thus, in order to improve the performance, reliability, and cost-effectiveness of electronics systems, an advanced packaging technology is being used for packaging of compound semiconductors.

Factors such as increase in demand for miniaturization of devices, improved system performance and optimization of compound semiconductor packaging, and emerging trends toward compound semiconductor wafers in the automotive industry are major factors driving the market growth to a certain extent.

However, high cost of compound semiconductor packaging is hampering its adoption is expected to pose a major threat to the compound semiconductor packaging market globally. However, emerging usage of compound semiconductors in smart technologies and emerging trends of fan-out wafer level packaging is expected to provide lucrative opportunities to the market growth globally.

The global packaging market for compound semiconductor is segmented into packaging platform, application, end user, and region. Based on packaging platform, the market is divided into flip-chip, embedded die, fan-in WLP, and fan-out WLP. On the basis of application, the packaging market for compound semiconductor is analyzed across CS power electronics, CS RF/Microwave, CS Photonics, CS Sensing, and CS Quantum.

By end user, the market is studies across digital economy, industrial and energy & power, defense/security, transport, consumer electronics, healthcare, and space. By region, the packaging market for compound semiconductor trends are analyzed across the U.S., the UK, China, and rest of the world.

The key players operating in the market includes Amkor Technology, Taiwan Semiconductor Manufacturing Company, Texas Instruments, Jiangsu Changjiang Electronics Tech Co., ASE Technology, KLA Corporation, Qorvo, Tokyo Electron Limited, Deca Technologies Inc., and Fujitsu Limited. These key players have adopted various strategies, such as product portfolio expansion, mergers & acquisitions, agreements, geographical expansion, and collaborations, to increase their market penetration and strengthen their foothold in the industry.

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Key Benefits For Stakeholders

This study comprises analytical depiction of the global packaging market size for compound semiconductor along with the current trends and future estimations to depict the imminent investment pockets.

The overall packaging market analysis for compound semiconductor is determined to understand the profitable trends to gain a stronger foothold.

The report presents information related to key drivers, restraints, and opportunities with a detailed impact analysis.

The current packaging market forecast for compound semiconductor is quantitatively analyzed from 2019 to 2027 to benchmark the financial competency.

Porter’s five forces analysis illustrates the potency of the buyers and the packaging market share for compound semiconductor of key vendors.

Packaging Market For Compound Semiconductor Key Segments

By Packaging Platform

Flip Chip

Embedded Die

Fan-In WLP

Fan-Out WLP

By Application

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Compound Semiconductor Power Electronics

Compound Semiconductor RF/Microwave

Compound Semiconductor Photonics

Compound Semiconductor Sensing

Compound Semiconductor Quantum

By End User

Digital Economy

Industrial and Energy & Power

Defense/Security

Transport

Consumer Electronics

Healthcare

Space

By Region

U.S.

UK

China

Rest of the World

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Key Market Players

Amkor Technology

ASE Technology

Deca Technologies Inc.

Fujitsu Limited

Jiangsu Changjiang Electronics Tech Co.

KLA Corporation

Qorvo

Taiwan Semiconductor Manufacturing Company

Texas Instruments

Tokyo Electron Limited

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